**SMD-Terminal block Pico with push wire contacts and contact opening function**

without insulating housing

1 pole - 46.110.1001.48**Funnel-shaped wire insertion channel for easy wire insertion****Direct insertion of solid and stranded, tinned wire ends and finely stranded conductors by using the contact opening function****Contact opening function** - also for release of already inserted wires**Mounting and wiring position: PCB top side****Machine-compatible "tape-and-reel" packaging**

Fixing: Lead-free reflow soldering according to DIN EN 610760-1, section 6

Material: CrNi / CuSn

Clamping spring material: CrNi

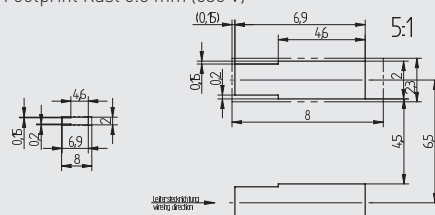
Contact material: CuSn

Contact surface: hot-dipped tinned

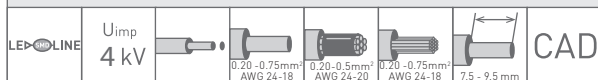
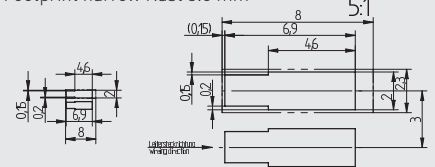
Note: Terminal without insulation housing!

Protection against contact when using voltage > extra-low voltage (SELV, PELV) must be ensured in the application.

Footprint Rast 6.5 mm (630 V)



Footprint narrow Rast 3.0 mm



Packaging data 46.110.1001.48	
Weight per piece	0.1 g
Pieces per coil - Tape and Reel	6.000
Reel width	16 mm
Pitch distance	4 mm
Reel diameter	330 mm - 13"
Weight per reel	1.3 kg
Number of reels per carton	18
Number of SMD terminal blocks per carton	108.000
Weight per carton	24.3 kg
Carton dimensions (LxWxH)	400 x 355 x 365 mm
Cartons per pallet	12
Pieces per pallet	1.296.000

Accessories:

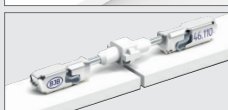
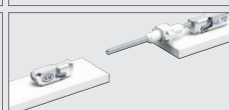
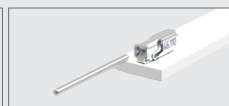
SMD Pico-B2B-connector. For connection of LED modules.

Tool for contact opening

To open contacts for use of finely stranded wires or for release of already inserted wires.

46.110.
46.131

46.131



46.110.U801.89

LED - Light and connection technology

SMD-Terminal block Pico General technical information

NEW**46.110**

Connection data

Connection technology	Push wire contacts
Solid wires	0.20 - 0.75 mm ² , AWG 24-18
Stranded, tinned wires	0.20 - 0.5 mm ² , AWG 24-20
Stranded wires	0.20 - 0.75 mm ² , AWG 24-18
Strip length	7.5 - 9.5 mm
Conductor entry angle to the PCB	0°
Wire release function by	Contact opening tool

Pull-out force according to DN 60999-1

0.2 mm ²	min. 10 N
0.34 mm ²	min. 15 N
0.5 mm ²	min. 20 N
0.75 mm ²	min. 30 N
Insertion force	max. 10 N

Geometrical data

Pin spacing	6.5 mm / 0.16 inch
Width	2.3 mm / 0.15 inch
Height	2.7 mm / 0.16 inch
Depth	8 mm / 0.52 inch

Material data

Insulating material group	-
Insulating material	-
PTI	-
Flammability class, based on UL 94	-
Clamping spring material	CrNi
Contact material	CuSn
Contact surface	hot-dipped tinned

Mechanical data

Mounting position	PCB top side
Mounting type	Lead-free reflow soldering

Temperature data

Marginal temperatures	-40 °C to + 150 °C
Ambient temperature	-40 °C to + 105 °C

Rated data according to IEC / EN 60947-7-4 (IEC/EN 60664-1). The data are based on the exemplary grid dimension of 6.5 mm.

Rated voltage (III / 3)	320 V
Rated impulse voltage (III / 3)	4 kV
Rated voltage (III / 2)	320 V
Rated impulse voltage (III / 2)	4 kV
Rated voltage (II / 2)	630 V
Rated impulse voltage (II / 2)	4 kV
Rated current	9 A

Rated data according to UL 1977

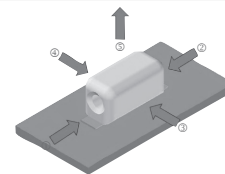
Rated voltage UL 1977	630 V
Rated current UL 1977	USR: 9 A
	CNR: 6 A, AWG 24
	CNR: 9 A, AWG 18

Country specific certificates

VDE ENEC	IEC 606947-7-4: 2019-10, IEC 60947-7-4:2019
UL  c  us	1977

Shear forces according to IEC 62137-1-2: 2007.

These values are maximum values that apply only for impuls, not for continuous load.



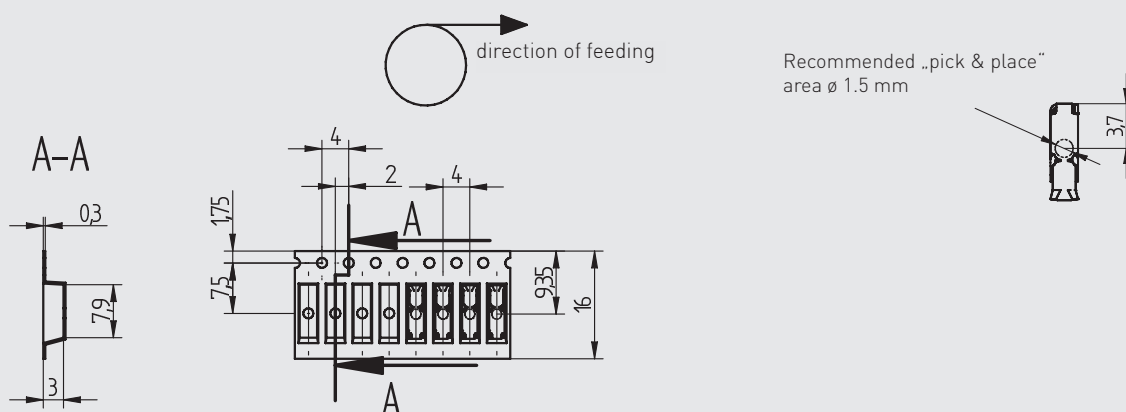
Direction 1 shear force along	50
Direction 2 shear force along	50
Direction 3 shear force across	30
Direction 4 shear force across	30
Direction 5 pull-off force	30

Instructions for soldering process

Suitable for leadfree-reflow-profiles according to DIN EN 61760-1 respective DIN EN 60068-2-58 up to peak-temperature of max. 260°C.

Due to different application-specific parameters (component arrangement and alignment, soldering system, solder paste), it is recommended to use test runs to determine a suitable profile under production conditions.

Depending on the SMD soldering process and associated parameters a minor discoloration might occur. However, this will not influence the functionality.



Storage time	Solderability up to 6 months when stored between -5°C and +40°C and rel. humidity between 10...60% r H. After a storage time of 6 months, solderability has to be checked according to J-STD-002D or DIN EN 60068-2-58:2016.
max. allowed number of reflow-processes	3
Reflow-profile	Reflow-profile (lead-free)
Solderability	Solderability of components is checked by wetting test according to J-STD-002D
Assembly method	SMD, according to drawing
Recommended solder stencil thickness	100 - 150 µm (recommendation BJB 150 µm)